

# DATASHEET

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## Procelerant CE738AE

**Extended Temperature Range COM Express Module** 

Based on the open PICMG standard, the RadiSys Procelerant <sup>™</sup> CE738A-E module provides low power and high performance over an extended temperature range of -25°C – 70°C, critical for temperature sensitive COM Express embedded applications. Paired with a RadiSys Procelerant CR carrier board, the RadiSys family of COM Express modules provides a final production or a design-specific development platform

#### **PICMG STANDARD**

COM Express is the PICMG standard for a Computer-On-Module (COM) base on new serial differential signaling technologies such as PCI Express, Serial ATA, USB 2.0, LVDS, and Serial DVO. The COM Express modular concept enables OEMs to reduce time to market by reducing the time spent on processor design and enabling OEMs to focus on their core competencies and product differentiation. The modularity provides the ability for an OEM to plan for feature changes, demand fluctuations and performance upgrades without having to re-design their product. The RadiSys COM Express modules can reduce service repair inventories, simplify debugging and reduce field service time contributing to the success of the product over its lifetime.

#### **APPLICATIONS**

RadiSys CE738A-E COM Express module is ideal for rugged embedded applications that require extended temperature operations in addition to the small footprint and modular flexibility benefits of COM Express. These modules are compact and reliable solutions for meeting the rigors of transportation, military, industrial and medical applications requirements.

#### CARRIER DESIGNS SUPPORTED BY RADISYS

Whether customers design their own carrier board or utilize RadiSys Design Services to design one, RadiSys supports the design each step of the way. Tools such as the Carrier Design Guide and Thermal Design Guide, as well as schematics and Gerber files are available for customers committed to using RadiSys Procelerant CE processor modules. Ask your RadiSys Sales Manager for more information.



#### FEATURE SUMMARY

- 1.4GHz Low Power Pentium M 738 combined with Intel 915GM Chipset on a COM Express Module
- Extended Temperature Range: -25°C to 70°C
- Intel ICH6M I/O Hub
- PICMG COM Express
  Compliant

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### **Procelerant CE738AE Specifications**

FEATURE	FUNCTION	DESCRIPTION	
PHYSICAL	Dimensions	95mm x 125mm – COM Express Basic Form Factor	
	Compliance	PICMG COM Express 1.0 Basic Form Factor, Type 2	
PROCESSOR	Options	LV Pentium-M 738	
	Performance	CE738A LV Pentium-M: 1.4GHz / 667MHz FSB/ 2MB Cache	
	Package	BGA	
	Power	10W (Processor only)	
CHIPSET	Supplier	Intel 915GM and ICH6M I/O Hub	
	Features	Integrated video, PCI, IDE, PCI-Express, SATA, USB, LPC, GPIO	
MEMORY	Туре	Single 200-pin SODIMM socket populated with 512MB memory	
	Capacity	Up to 1GB DDR2 in a single channel	
BIOS	Туре	1MB, Phoenix Technologies	
AUDIO	Compliance	AC ' 97 Intel High Definition Audio via ICH6M I/O Hub	
VIDEO	Туре	Dual Independent Displays via Intel 915GM Chipset	
	Features	Dual SVDO, LVDS 18-bit dual channel, Analog VGA, TV Out	
	External	PCI-Express x16 Graphics Port, Multi-plexed on SDVO interface pins	
NETWORKING	Туре	IEEE 802.3 10/100/1000BaseT Compliant Physical Layer via Intel 82573V - Utilizes (1) PCI-Express x1 interface	
VO	USB	Eight USB 2.0 / 1.1 Ports	
	SATA	One SATA 150 Port	
	IDE	One Ultra ATA 100/66/33 Ports	
	Other	LPC, Smbus/I2C Bus,	
SUPER I/O	BIOS Support	National Semiconductor PC8374, Ask about support for Winbond W83627HF-AW	
EXPANSION	PCI Express	3*PCI-Express x1 and 1*PCI-Express x16	
	PCI	PCI 2.3 32-bit 33MHz, four logical devices	
CONNECTORS	COM Express	(2) 220 pin COM Express standard connectors.	
POWER	Input	12V	
	Dissipation	20.7W	
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3D Mark (Max)

#### PHYSICAL SPECIFICATIONS

ENVIRONMENT	Temperature	Operating	–25° to 70°C	
		Non-Operating	-40° – 85°C	
	Humidity	Condensing	5%-95%	
		Non- Condensing	5% - 90% RH at 40C	
	Shock	Operating	30G, half sine 11ms duration	
		Storage	50G, half sine 11ms duration 30G	
	Vibration	Operating	5-2000Hz Random, 0.5g, 10min min. in each of 3 axes	
		Non-Operating	5g acceleration over 5-2000Hz Sine Wave (P-P), 1 oct/min Sine Sweep	
REGULATORY	Safety	UL60950-1, EN60950-1, IEC60950-1		
	EMC	EN55022, EN55024, and FCC Part 15, Subpart B, Class B		
WARRANTY	Standard	Two years, parts only		

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#### **Ordering Information**

CE-PHS17A: Low Profile Passive

CE-DVI-VGA: DVI to VGA cable

Call for pricing and availability. Refer to the order codes below. Module Order Codes: **CE738A-E-512** 1.4Ghz LV Pentium-M, -25°C - 70°C Temperature Range, 512MB Supporting Products: **CR202-PCIE16**: Development ATX carrier board with 16-bit PCI-Express **CE-PHSA**: Passive Heatsink & Assembly

**CE-TIM:** Thermal Interface Material, required with Heatsinks

**RadiSys** 

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